



Material Content Data Sheet



Sales Product Name		TLE6258-2G		Issued		20. July 2018		
MA#		MA000977658						
Package		PG-DSO-8-16		Weight*		83.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.405	2.89	2.89	28869	28869
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8607	
wire	non noble metal	copper	7440-50-8	29.121	34.95	35.86	349499	358644
	noble metal	gold	7440-57-5	0.174	0.21	0.21	2090	2090
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.12		1155
encapsulation	plastics	epoxy resin	-	4.425	5.31		53113	
	inorganic material	silicondioxide	60676-86-0	43.581	52.30	57.73	523045	577313
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9767	9767
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7804	7804
glue	plastics	acrylic resin	-	0.284	0.34		3413	
	noble metal	silver	7440-22-4	1.008	1.21	1.55	12100	15513
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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